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# EVERFUSE™

Polymeric PTC Fuse

Product: SHV2920P500/30-AA  
Revision: C  
Date: 25 October, 2016  
Page: 1 of 1

## Device Specification (preliminary)



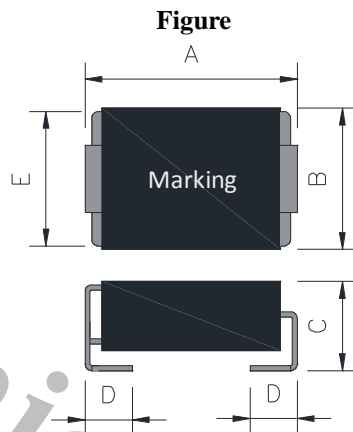
Polytronics Technology Corp  
REGISTERED TO QS9000, TL9000  
ISO9001 (version 2000), and ISO 14001  
CERTIFICATE NO. AB727 and A16971

### Electrical Rating

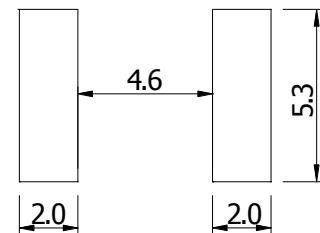
Voltage: 30V  
Current: 30A

### Marking :

P (Polytronics / Polystar Logo)



### Recommended Pad Layout (mm)



### Physical Dimensions (mm)

Part Number	A		B		C		D		E	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
SHV2920P500/30-AA	6.70	8.60	5.00	5.70	2.00	3.20	1.00	2.30	4.90	5.30

### Electrical Characteristics

Part Number	I <sub>hold</sub> (A)	I <sub>trip</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	P <sub>d typ</sub> (W)	Maximum Time-to-Trip		Resistance (Ω)	
						(A)	(Sec)	R <sub>min</sub>	R <sub>I<sub>max</sub></sub>
SHV2920P500/30-AA	5.0	12.5	30	30	3.5	25.0	10.0	0.003	0.020

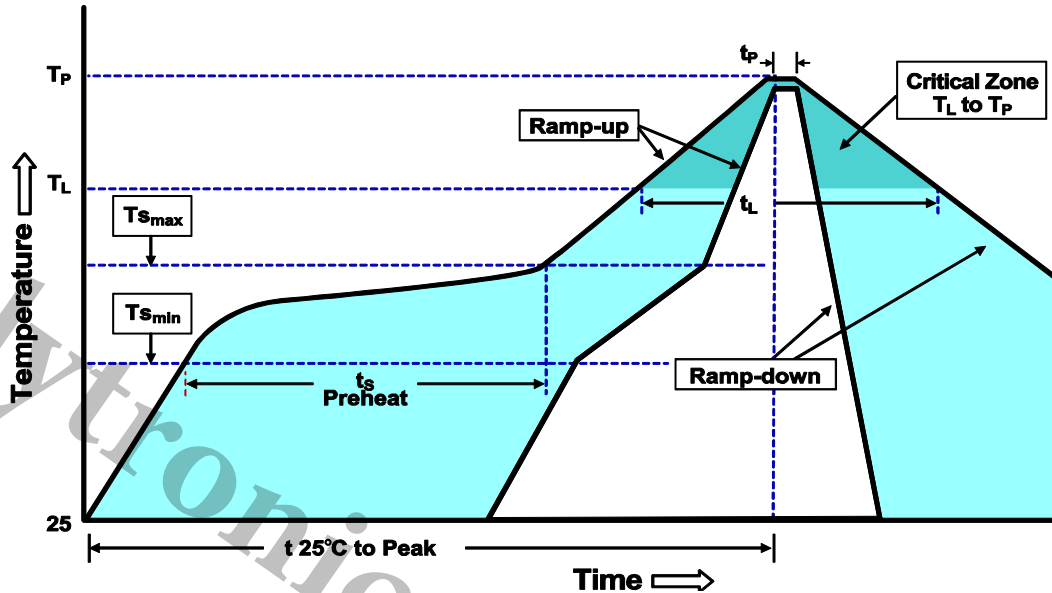
- Note: I<sub>hold</sub> = Hold current: maximum current device will pass without tripping in 25°C still air.  
 I<sub>trip</sub> = Trip Current: minimum current at which the device will trip in 25°C still air.  
 V<sub>max</sub> = Maximum voltage device can withstand without damage at rated current (I<sub>max</sub>)  
 I<sub>max</sub> = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>)  
 P<sub>d</sub> = Power dissipated from device when in the tripped state at 25°C still air.  
 R<sub>min</sub> = Minimum resistance of device in initial (un-soldered) state.  
 R<sub>I<sub>max</sub></sub> = Maximum resistance of device reflow soldering of 260°C for 20 sec.  
 \*Value specified were determined using the PWB with 0.150" \*1.5oz copper traces.

**Caution** : Operation beyond the specified rating may result in damage and possible arcing and flame.

© Specifications are subject to change without notice.



## Soldering Parameters



Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (TS <sub>max</sub> to TP)	3°C/second max.
Preheat	
-Temperature Min (TS <sub>min</sub> )	150°C
-Temperature Max (TS <sub>max</sub> )	200°C
-Time (TS <sub>min</sub> to TS <sub>max</sub> )	60-180 seconds
Time maintained above:	
-Temperature (TL)	217°C
-Time (t <sub>L</sub> )	60-150 seconds
Peak Temperature (TP)	260°C
Time within 5°C of actual Peak Temperature (t <sub>p</sub> )	20-40 seconds
Ramp-Down Rate	6 °C /second max.
Time 25°C to Peak Temperature	8 minutes max.
Storage Condition	0°C ~35°C, ≤70%RH

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N<sub>2</sub> environment for lead-free
- Recommended maximum paste thickness is 0.25mm (0.010 inch)
- Devices can be cleaned using standard industry methods and solvents.

**Note 1:** All temperature refer to topside of the package, measured on the package body surface.

**Note 2:** If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.